

HGTD7N60C3, HGTD7N60C3S, HGTP7N60C3

January 1997

14A, 600V, UFS Series N-Channel IGBTs

Features

- 14A, 600V at T_C = 25^oC
- 600V Switching SOA Capability
- Typical Fall Time140ns at T_J = 150°C
- · Short Circuit Rating
- Low Conduction Loss

Description

The HGTD7N60C3, HGTD7N60C3S and HGTP7N60C3 are MOS gated high voltage switching devices combining the best features of MOSFETs and bipolar transistors. These devices have the high input impedance of a MOSFET and the low on-state conduction loss of a bipolar transistor. The much lower on-state voltage drop varies only moderately between 25°C and 150°C.

The IGBT is ideal for many high voltage switching applications operating at moderate frequencies where low conduction losses are essential, such as: AC and DC motor controls, power supplies and drivers for solenoids, relays and contactors.

PACKAGING AVAILABILITY

PART NUMBER	PACKAGE	BRAND		
HGTD7N60C3	TO-251AA	G7N60C		
HGTD7N60C3S	TO-252AA	G7N60C		
HGTP7N60C3	TO-220AB	G7N60C3		

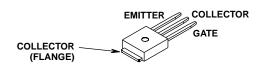
NOTE: When ordering, use the entire part number.

Add the suffix 9A to obtain the TO-252AA variant in tape and reel, i.e. HGTD7N60C3S9A.

Formerly Developmental Type TA49115.

Packaging JEDEC TO-220AB EMITTER COLLECTOR GATE COLLECTOR (FLANGE)

JEDEC TO-251AA

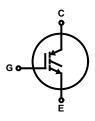


JEDEC TO-252AA



Terminal Diagram

N-CHANNEL ENHANCEMENT MODE



Absolute Maximum Ratings T_C = 25°C, Unless Otherwise Specified

	HGTD7N60C3, HGTD7N60C3S	3
	HGTP7N60C3	UNITS
Collector-Emitter Voltage	s 600	V
Collector Current Continuous		
At $T_C = 25^{\circ}C$	5 14	Α
At T _C = 110°C		Α
Collector Current Pulsed (Note 1)	M 56	Α
Gate-Emitter Voltage ContinuousV _{GE}	s ±20	V
Gate-Emitter Voltage Pulsed	M ±30	V
Switching Safe Operating Area at T _J = 150°C, Figure 14SSO	A 40A at 480V	
Power Dissipation Total at T _C = 25°C	D 60	W
Power Dissipation Derating T _C > 25°C	. 0.48	W/oC
Reverse Voltage Avalanche Energy E _{AR}		mJ
Operating and Storage Junction Temperature Range	G -40 to 150	°С
Maximum Lead Temperature for SolderingT	L 260	οС
Short Circuit Withstand Time (Note 2) at V _{GE} = 15V	C 1	μs
Short Circuit Withstand Time (Note 2) at V _{GE} = 10V	C 8	μs
NOTES:		

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. $V_{CE(PK)} = 360V$, $T_J = 125^{\circ}C$, $R_{GE} = 50\Omega$.

HGTD7N60C3, HGTD7N60C3S, HGTP7N60C3

$\textbf{Electrical Specifications} \hspace{0.5cm} \textbf{T}_{C} = 25^{o}\text{C, Unless Otherwise Specified}$

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Collector-Emitter Breakdown Voltage	BV _{CES}	$I_C = 250\mu A, V_{GE} = 0V$		600	-	-	V
Emitter-Collector Breakdown Voltage	BV _{ECS}	$I_C = 3mA$, $V_{GE} = 0V$		16	30	-	V
Collector-Emitter Leakage Current	I _{CES}	V _{CE} = BV _{CES}	$T_{\rm C} = 25^{\rm o}{\rm C}$	=	-	250	μΑ
		V _{CE} = BV _{CES}	$T_{C} = 150^{\circ}C$	-	-	2.0	mA
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	I _C = I _{C110} , V _{GE} = 15V	$T_{C} = 25^{\circ}C$	=	1.6	2.0	V
			$T_{\rm C} = 150^{\rm o}{\rm C}$	=	1.9	2.4	V
Gate-Emitter Threshold Voltage	V _{GE(TH)}	$I_C = 250\mu A,$ $V_{CE} = V_{GE}$	$T_C = 25^{\circ}C$	3.0	5.0	6.0	V
Gate-Emitter Leakage Current	I _{GES}	V _{GE} = ±25V		-	-	±250	nA
Switching SOA	SSOA	$T_J = 150^{\circ}\text{C}$ $R_G = 50\Omega$ $V_{GE} = 15V$ $L = 1\text{mH}$	V _{CE(PK)} = 480V	40	-	-	Α
			V _{CE(PK)} = 600V	6	-	-	А
Gate-Emitter Plateau Voltage	V _{GEP}	$I_{C} = I_{C110}, V_{CE} = 0.5 \text{ BV}_{CES}$		=	8	-	V
On-State Gate Charge	Q _{G(ON)}	$I_{C} = I_{C110},$ $V_{CE} = 0.5 \text{ BV}_{CES}$	V _{GE} = 15V	-	23	30	nC
			V _{GE} = 20V	-	30	38	nC
Current Turn-On Delay Time	t _{D(ON)I}	$T_J = 150^{\circ}C$ $I_{CE} = I_{C110}$ $V_{CE(PK)} = 0.8 \text{ BV}_{CES}$ $V_{GE} = 15V$ $R_G = 50\Omega$		-	8.5	-	ns
Current Rise Time	t _{RI}			-	11.5	-	ns
Current Turn-Off Delay Time	t _{D(OFF)} I			-	350	400	ns
Current Fall Time	t _{Fl}	L = 1.0mH	-	140	275	ns	
Turn-On Energy	E _{ON}	1	-	165	-	μJ	
Turn-Off Energy (Note 3)	E _{OFF}			-	600	-	μJ
Thermal Resistance	$R_{ heta JC}$			-	-	2.1	°C/W

NOTE:

HARRIS SEMICONDUCTOR IGBT PRODUCT IS COVERED BY ONE OR MORE OF THE FOLLOWING U.S. PATENTS:

4,364,073 4,417,385 4,430,792 4,443,931 4,466,176 4,516,143 4,532,534	4,567,641
4,587,713 4,598,461 4,605,948 4,618,872 4,620,211 4,631,564 4,639,754	4,639,762
4,641,162 4,644,637 4,682,195 4,684,413 4,694,313 4,717,679 4,743,952	4,783,690
4,794,432 4,801,986 4,803,533 4,809,045 4,809,047 4,810,665 4,823,176	4,837,606
4,860,080 4,883,767 4,888,627 4,890,143 4,901,127 4,904,609 4,933,740	4,963,951

^{3.} Turn-Off Energy Loss (E_{OFF}) is defined as the integral of the instantaneous power loss starting at the trailing edge of the input pulse and ending at the point where the collector current equals zero (I_{CE} = 0A). The HGTD7N60C3, HGTD7N60C3S and HGTP7N60C3 were tested per JEDEC standard No. 24-1 Method for Measurement of Power Device Turn-Off Switching Loss. This test method produces the true total Turn-Off Energy Loss. Turn-On losses include diode losses.

Typical Performance Curves PULSE DURATION = 250 μ s, DUTY CYCLE <0.5%, T_C = 25°C 40 COLLECTOR-EMITTER CURRENT (A) DUTY CYCLE <0.5%, V_{CE} = 10V COLLECTOR-EMITTER CURRENT (A) $V_{GE} = 15.0V$ 12.0V PULSE DURATION = 250µs 35 35 30 30 10.0V 25 25 $T_{C} = 150^{\circ}C$ 20 20 $T_C = 25^{\circ}C$ 9.0V 15 15 $T_C = -40^{\circ}C$ 8.5V 10 10 8.0V 5 7.5V Ë, Ë 7.0V 10 14 0 V_{GE}, GATE-TO-EMITTER VOLTAGE (V) V_{CE}, COLLECTOR-TO-EMITTER VOLTAGE (V) FIGURE 1. TRANSFER CHARACTERISTICS FIGURE 2. SATURATION CHARACTERISTICS 40 PULSE DURATION = 250µs PULSE DURATION = $250\mu s$ COLLECTOR-EMITTER CURRENT (A) DUTY CYCLE <0.5%, V_{GE} = 10V **DUTY CYCLE <0.5%, V_{GE} = 15V** COLLECTOR-EMITTER CURRENT 35 35 T_C = 25°C $T_C = -40^{\circ}C$ 30 30 25 25 $T_{C} = -40^{\circ}C$ 20 20 T_C = 150°C 15 15 T_C = 150°C 10 10 T_C = 25°C 5 5 <u>ű</u> <u>ë</u> V_{CE}, COLLECTOR-TO-EMITTER VOLTAGE (V) V_{CE}, COLLECTOR-TO-EMITTER VOLTAGE (V) FIGURE 3. COLLECTOR-EMITTER ON - STATE VOLTAGE FIGURE 4. COLLECTOR-EMITTER ON - STATE VOLTAGE 15 SHORT CIRCUIT WITHSTAND TIME (µS) V_{GE} = 15V $V_{CE} = 360V, R_{GE} = 50\Omega, T_{J} = 125^{\circ}C$ CURRENT(A) I_{CE}, DC COLLECTOR CURRENT (A) 12 120 Isc PEAK SHORT CIRCUIT 80 60 tsc <u>Ş</u> 40 25 50 75 100 125 10 T_C, CASE TEMPERATURE (°C) V_{GE}, GATE-TO-EMITTER VOLTAGE (V) FIGURE 5. MAXIMUM DC COLLECTOR CURRENT AS A FIGURE 6. SHORT CIRCUIT WITHSTAND TIME **FUNCTION OF CASE TEMPERATURE**

Typical Performance Curves (Continued) 500 $T_{.I} = 150^{\circ}C$, $R_G = 50\Omega$, L = 1mH, $V_{CE(PK)} = 480V$ $T_J = 150^{\circ}C$, $R_G = 50\Omega$, L = 1mH, $V_{CE(PK)} = 480V$ t_{D(OFF)I}, TURN-OFF DELAY TIME (ns) t_{D(ON)I}, TURN-ON DELAY TIME (ns) 450 400 350 20 V_{GE} = 10V V_{GE} = 10V OR 15V 300 V_{GE} = 15V 250 200 I_{CE}, COLLECTOR-EMITTER CURRENT (A) I_{CE}, COLLECTOR-EMITTER CURRENT (A) FIGURE 7. TURN-ON DELAY TIME AS A FUNCTION OF FIGURE 8. TURN-OFF DELAY TIME AS A FUNCTION OF **COLLECTOR-EMITTER CURRENT COLLECTOR-EMITTER CURRENT** 300 $T_J = 150^{\circ}C$, $R_G = 50\Omega$, L = 1mH, $V_{CE(PK)} = 480V$ $T_J = 150^{\circ}C$, $R_G = 50\Omega$, L = 1mH, $V_{CE(PK)} = 480V$ (ns) 250 V_{GE} = 10V 100 **TURN-ON RISE TIME** FALL TIME (ns) 200 V_{GE} = 10V or 15V V_{GE} = 15V 150 ij, 100 20 11 14 20 I_{CE}, COLLECTOR-EMITTER CURRENT (A) I_{CE}, COLLECTOR-EMITTER CURRENT (A) FIGURE 9. TURN-ON RISE TIME AS A FUNCTION OF FIGURE 10. TURN-OFF FALL TIME AS A FUNCTION OF **COLLECTOR-EMITTER CURRENT COLLECTOR-EMITTER CURRENT** 2000 3000 $T_J = 150^{\circ}C$, $R_G = 50\Omega$, L = 1mH, $V_{CE(PK)} = 480V$ $T_J = 150^{\circ}C$, $R_G = 50\Omega$, L = 1mH, $V_{CE(PK)} = 480V$ 3 E_{ON}, TURN-ON ENERGY LOSS (μJ) 1000 E_{OFF}, TURN-OFF ENERGY LOSS V_{GE} = 10V 1000 500 V_{GE} = 15V V_{GF} = 10V or 15V 500 100 100 5 8 11 20 20 11 14 I_{CE}, COLLECTOR-EMITTER CURRENT (A) I_{CE}, COLLECTOR-EMITTER CURRENT (A)

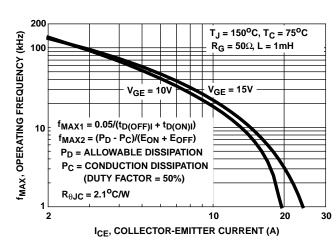
FIGURE 12. TURN-OFF ENERGY LOSS AS A FUNCTION OF

COLLECTOR-EMITTER CURRENT

FIGURE 11. TURN-ON ENERGY LOSS AS A FUNCTION OF

COLLECTOR-EMITTER CURRENT

Typical Performance Curves (Continued)



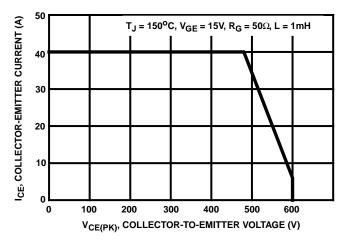
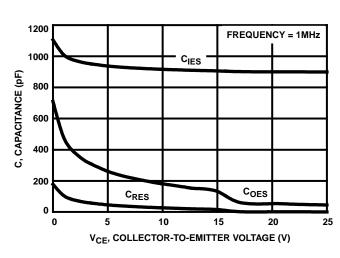


FIGURE 13. OPERATING FREQUENCY AS A FUNCTION OF COLLECTOR-EMITTER CURRENT

FIGURE 14. MINIMUM SWITCHING SAFE OPERATING AREA



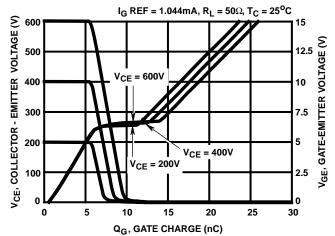


FIGURE 15. CAPACITANCE AS A FUNCTION OF COLLECTOR-EMITTER VOLTAGE

FIGURE 16. GATE CHARGE WAVEFORMS

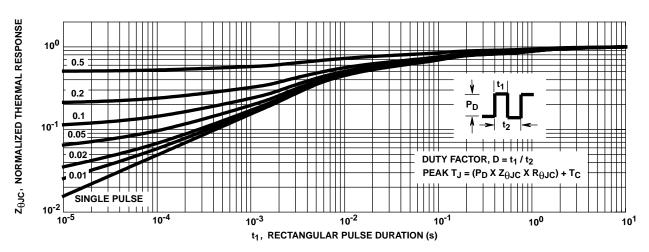


FIGURE 17. IGBT NORMALIZED TRANSIENT THERMAL IMPEDANCE, JUNCTION TO CASE

Test Circuit and Waveform

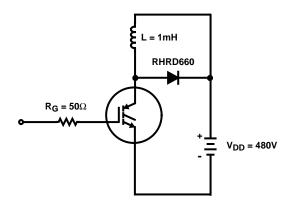


FIGURE 18. INDUCTIVE SWITCHING TEST CIRCUIT

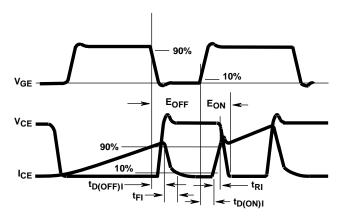


FIGURE 19. SWITCHING TEST WAVEFORMS

Handling Precautions for IGBTs

Insulated Gate Bipolar Transistors are susceptible to gate-insulation damage by the electrostatic discharge of energy through the devices. When handling these devices, care should be exercised to assure that the static charge built in the handler's body capacitance is not discharged through the device. With proper handling and application procedures, however, IGBTs are currently being extensively used in production by numerous equipment manufacturers in military, industrial and consumer applications, with virtually no damage problems due to electrostatic discharge. IGBTs can be handled safely if the following basic precautions are taken:

- Prior to assembly into a circuit, all leads should be kept shorted together either by the use of metal shorting springs or by the insertion into conductive material such as "ECCOSORBD™ LD26" or equivalent.
- 2. When devices are removed by hand from their carriers, the hand being used should be grounded by any suitable means for example, with a metallic wristband.
- 3. Tips of soldering irons should be grounded.
- Devices should never be inserted into or removed from circuits with power on.
- Gate Voltage Rating Never exceed the gate-voltage rating of V_{GEM}. Exceeding the rated V_{GE} can result in permanent damage to the oxide layer in the gate region.
- 6. Gate Termination The gates of these devices are essentially capacitors. Circuits that leave the gate open-circuited or floating should be avoided. These conditions can result in turn-on of the device due to voltage buildup on the input capacitor due to leakage currents or pickup.
- Gate Protection These devices do not have an internal monolithic Zener diode from gate to emitter. If gate protection is required an external Zener is recommended.

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Operating Frequency Information

Operating Frequency Information for a Typical Device

Figure 13 is presented as a guide for estimating device performance for a specific application. Other typical frequency vs collector current (I_{CE}) plots are possible using the information shown for a typical unit in Figures 4, 7, 8, 11 and 12. The operating frequency plot (Figure 13) of a typical device shows f_{MAX1} or f_{MAX2} whichever is smaller at each point. The information is based on measurements of a typical device and is bounded by the maximum rated junction temperature.

 f_{MAX1} is defined by $f_{MAX1} = 0.05/(t_{D(OFF)I} + t_{D(ON)I}).$ Deadtime (the denominator) has been arbitrarily held to 10% of the on- state time for a 50% duty factor. Other definitions are possible. $t_{D(OFF)I}$ and $t_{D(ON)I}$ are defined in Figure 19.

Device turn-off delay can establish an additional frequency limiting condition for an application other than T_{JMAX} . $t_{D(OFF)I}$ is important when controlling output ripple under a lightly loaded condition.

 f_{MAX2} is defined by $f_{MAX2}=(P_D-P_C)/(E_{OFF}+E_{ON}).$ The allowable dissipation (P_D) is defined by $P_D=(T_{JMAX}-T_C)/R_{\theta JC}.$ The sum of device switching and conduction losses must not exceed $P_D.$ A 50% duty factor was used (Figure 13) and the conduction losses (P_C) are approximated by $P_C=(V_{CE}\times I_{CE})/2.$ E_{ON} and E_{OFF} are defined in the switching waveforms shown in Figure 19. E_{ON} is the integral of the instantaneous power loss ($I_{CE}\times V_{CE}$) during turn-on and E_{OFF} is the integral of the instantaneous power loss ($I_{CE}\times V_{CE}$) during turn-off. All tail losses are included in the calculation for E_{OFF} ; i.e. the collector current equals zero ($I_{CE}=0$).